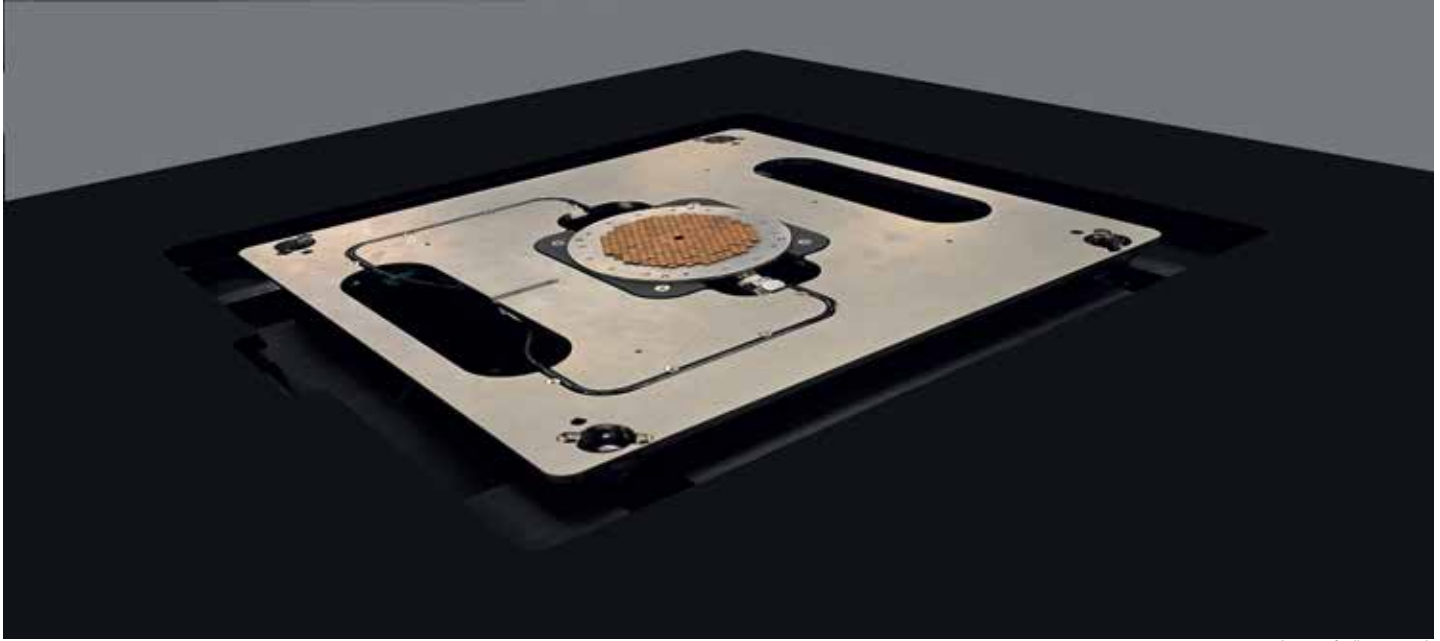


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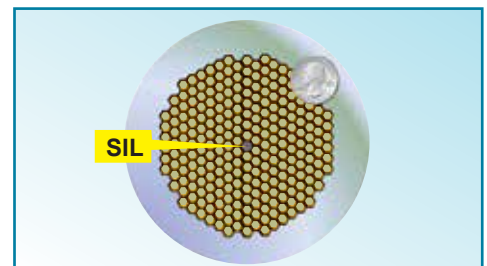
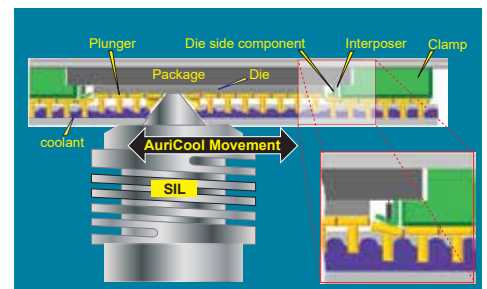
The **COOLING SYSTEM** for **DYNAMIC LASER TECHNIQUE** & **LASER WAVEFORM PROBING**



photos are for illustration only

Features

- Patented design to remove heat from active DUT during analysis. US Patent No.: US 9,917,034
- Proprietary thermal interface and heat extraction with closed loop chiller
- Capable of handling >200 W of heat flux
- Option for cooling larger die sizes (Up to 40x40mm and beyond)
- Compatible with SIL and air gap lenses with optical axis window
- Accommodates die-side components with flexible pins



AuriCool Head

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